2004/06/18 10:35 2004/06/18 11:09 2004/06/18 12:06 2004/06/18 10:42
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2004/06/18 12:02
2004/06/18 13:08
2004/00/18 13:08
2004/06/18 12:05
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2004/06/18 12:06

13	86	(((contact near (hole via open\$3)) and electroplate)) and capacitor\$1	USPAT;	2004/06/18 13:09
"	00	(((voltate field (1010 114 openios)) and electropides)) and superiors.	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
14	26	((((contact near (hole via open\$3)) and electroplate)) and capacitor\$1)	USPĀT;	2004/06/18 12:06
		and ((lower bottom) near electrode)	US-PGPUB,	
		, , ,	ЕРО, ЈРО,	
			DERWENT;	
			IBM_TDB	
15	1	(((depost\$3 fill\$3) near contact near (hole via open\$3)) near2	USPAT;	2004/06/18 13:10
		electroplate)	US-PGPUB,	
		• /	ЕРО; ЛРО;	
	· ·		DERWENT;	
			IBM_TDB	
17	1	(depost\$3 fill\$3) and ((contact near (hole via open\$3)) near2	USPAT;	2004/06/18 13:10
		electroplate)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
16	267	(((contact near (hole via open\$3)) and electroplate)) and (deposit\$3	USPAT;	2004/06/18 13:36
		fill\$3)	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
-			IBM_TDB	
18	26	etch\$3 with (gas\$2 near5 (O2 oxygen Cl2 BCl3 Ar HBr) near5 ((top	USPAT;	2004/06/18 13:59
•		upper) near electrode))	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
1			IBM_TDB	2004/06/19 12:20
19	2	("6376386").PN.	USPAT;	2004/06/18 13:39
			US-PGPUB;	·
			EPO; JPO;	
			DERWENT;	
		4 1 02 - 1/41 (022 (O2	IBM_TDB USPAT;	2004/06/18 13:59
20	0	etch\$3 with (gas\$2 near2 (O2 oxygen) near5 (Cl2 BCl3 Ar HBr) near5	US-PGPUB;	2004/00/10 13.39
	1	((top upper) near electrode))	EPO; JPO;	
}			DERWENT;	
			IBM_TDB	
1	İ			